



Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 14.0052

CB Certificate No.: 029/ICA

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Test Reports:

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Board Types	Multilayer boards with blind and/or buried vias (Type 4) Multilayer boards without blind or buried vias (Type 3) Double-sided boards (Type 2) Single-sided boards (Type 1)	IPC 6012 Class 3
Base Materials:	Epoxide woven glass IPC 4101/26 (21, 24, 98, 99, 101, 126)	
Board Size:	405 mm x 280 mm (Type 3 & 4) 500 mm x 360 mm (Type 1 & 2)	
Conductors:	Minimum width: 0.1 mm \pm 0.05mm Minimum spacing: 0.1 mm \pm 0.05mm	
Number of Layers:	16 (Class 2), 12 (Class 3) Maximum	
Plated-through hole Diameter:	0.5 mm minimum drilled	
Aspect Ratio:	6.4 : 1 (Class 2), 4.6 : 1 (Class 3) Maximum	
Finishes:	63:37 Sn/Pb Hot Air Solder Level Electroless Nickel / Immersion Gold Electrolytic Nickel and Gold Organic Solderability Preservative Immersion Silver Photoimageable liquid polymer solder resist IR Cured Notation Ink	
Additional:	Bonded Heatplanes: Anodized Aluminium Nickel Plated Copper	

Note: It may not be possible to achieve the limits of the capability in combination. Such combinations are determined by the agreed customer detail specification for the PCB ordered.

This schedule is only valid in conjunction with the referenced Certificate of Approval

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